



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-05-06
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STF5N80K5	CCFP*VK81B52	A	SHENZHEN B/E	2016-05-06
	Amount	UoM	Unit type	ST ECOPACK Grade
	1900.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10-9.05-4.4	3	THROUGH HOLE	
Comment	TO 220 ISO FULL PACK IN LINE			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	CCFP*VK81B52					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	2.783	mg	supplier	die	Silicon (Si)	7440-21-3		2.624	mg	942888	1382
				supplier	metallization	Aluminium (Al)	7429-90-5		0.068	mg	24425	36
				supplier	Passivation	Silicon Nitride	12033-89-5		0.016	mg	5747	8
				supplier	Passivation	Silicon Oxide	7631-86-9		0.039	mg	14009	21
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	718	1
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.025	mg	8980	13
Leadframe	Copper & its alloys	1253.005	mg	supplier	back side metallization	Silver (Ag)	7440-22-4		0.009	mg	3233	5
				supplier	alloy	Copper (Cu)	7440-50-8		1251.376	mg	998700	658619
				supplier	alloy	Iron (Fe)	7439-89-6		1.253	mg	1000	659
Soft solder	Solder	3.555	mg	supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.376	mg	300	198
				JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.395	mg	954993	1787
				supplier	solder	Silver (Ag)	7440-22-4		0.089	mg	25035	47
				supplier	solder	Tin (Sn)	7440-31-5		0.071	mg	19972	37
Bonding wires	Other inorganic materials	0.310	mg	supplier	wire	Copper (Cu)	7440-50-8		0.310	mg	1000000	163
Encapsulation	Other Organic Materials	633.985	mg	supplier	mold compound	Quartz	14808-60-7		443.789	mg	699999	233573
				supplier	mold compound	Silica, vitreous	60676-86-0		47.549	mg	75000	25026
				supplier	mold compound	Epoxy resin	25068-38-6		88.758	mg	140000	46715
				supplier	mold compound	phenol resin	29690-82-2		44.379	mg	70000	23357
				supplier	mold compound	metal hydroxide	21645-51-2		6.340	mg	10000	3337
Connections coating	Solder	6.362	mg	supplier	mold compound	carbon black	1333-86-4		3.170	mg	5001	1668
				supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348